

July 8, 2003

To: Commissioner of Patents and Trademarks  
Washington, D.C. 20231

Fr: George O. Saile     Reg. No. 19,572  
28 Davis Avenue  
Poughkeepsie, N.Y. 12603

Subject:

**Divisional Patent Application of**

Serial No.: 09/953,544 9/17/01

JIN-YUAN LEE

A STRUCTURE OF HIGH PERFORMANCE COMBO  
CHIP AND PROCESSING METHOD

**PRELIMINARY AMENDMENT**

Dear Sir:


This is a preliminary amendment for the above referenced Divisional Patent  
Application. Please amend the above identified application for patent as follows:

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with the United States  
Postal Service as first class mail in an envelope addressed to: Commissioner of Patents  
and Trademarks, Washington, D.C. 20231, on July 8, 2003.

Stephen B. Ackerman, Reg. No. 37,761

Signature/Date

 8 July 2003